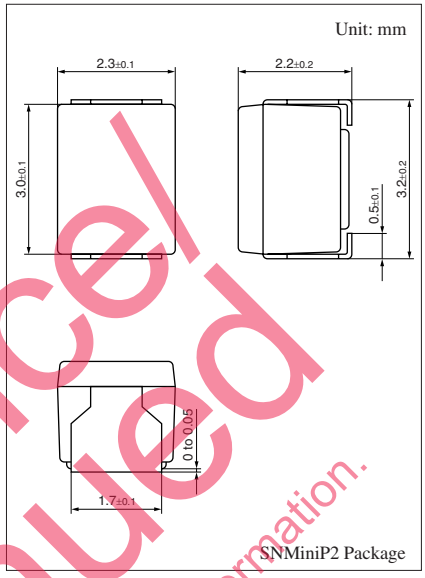
UNHS206

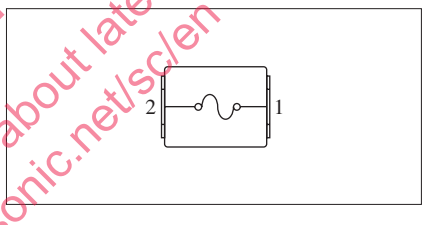
Circuit Protector Elements

For overcurrent protection



Marking Symbol: 2.3

Lead Connection



■ Features

- Sharp cutoff characteristics and low voltage drop
- Flame retardant package and low heat generation, high density mounting is possible.

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Operating ambient temperature	T_{opr}	−55 to +125	°C
Storage temperature	T_{stg}	−55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

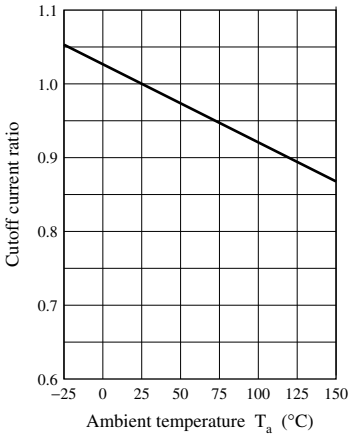
Parameter	Min	Typ	Max	Unit
Rated voltage		50		V
Rated current		2.3		A
Internal Resistance	17	22	27	mΩ
Cutoff current *		4.6		A

Note) ∗: Measurement condition of cutoff current shall be at $T_a = 25°C$, t = 1 s
Tolerance of cutoff current shall be ± 20%

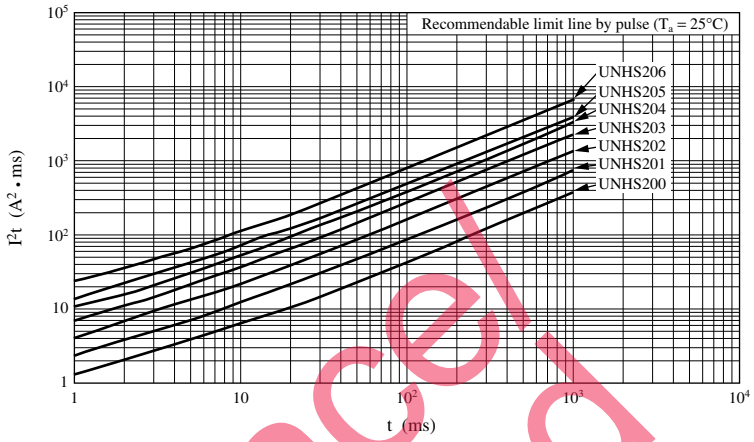
■ Usage Notes

- Package shall be overheated and dangerous for overcurrent.
- This device should be used only to the secondary circuit.
  Package will be damaged for added overpower.
- This device is not electrical fuse legally. Please draw a clear line between electrical fuse from this device.

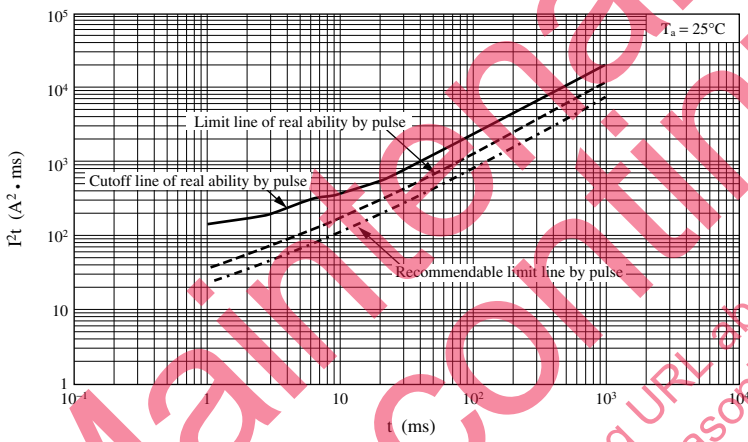
Cutoff current ratio — T_a



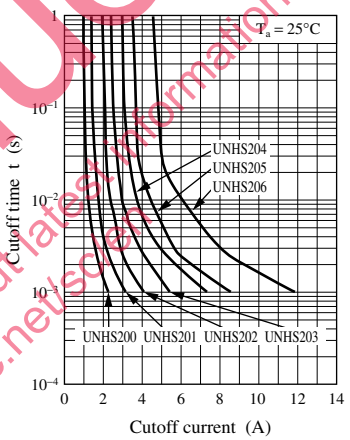
I^2t — t



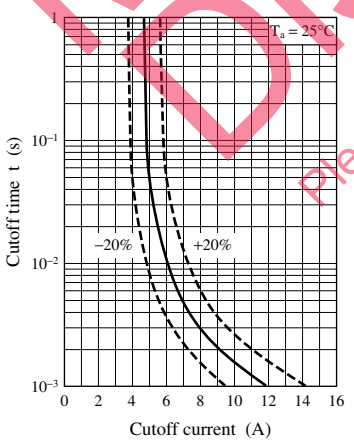
I^2t — t



Cutoff current characteristics



Cutoff current characteristics



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Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.